ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®	© Co	terial Compo pyright 2005. IPC, Bannoc ternational and Pan-Ameri	kburn, Illinois	. All rights reserve	tion with lower	level p	arts, the	declaratior	n encom	npasses	all lower		erials for	which th	e item is an assembly ne manufacturer has eclaration.	
1752-2 1.1	ion on IPC <mark>75x</mark>	C-1752 Standard			-			eclaration Class * ass 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informa								
Supplier Information																
Company Name *		Company Unique ID		Unique ID Au	ıthority	Respo	nse Date	e *	F	Respons	se Docur	ment ID				
SEMTECH CORPORATION	ON	00-847-9941		DUNS		2014-1	0-21									
Contact Name * Roya Motamedi		Title - Contact  Quality Customer Se	mico Spac				Email - Contact * rmotamedi@semtech.com				uplicate	Contact -	-> Autho	rized Re	presentative	
Authorized Representati		Title - Representative	Phone - Rep	Email - Representative *				Supplier Comments or URL for Additional Information								
Roya Motamedi		Quality Customer Se		· -	rmotamedi@semtech.com				Juppliel	Comme	THIS OF OTEL	_ 101 Au	andoriai ii	normanori		
Requester Item Numbe	r	Mfr Item Number		Mfr Item Name	Effectiv	e Date	Version Manufa		facturing Site		Weight *	UC	DM	Unit Type		
		SC414MLTRT		6A Integrated	FET Regulator w	i						45.6	mg	)	Each	
Alternate Recommendation Alternate Item Comments																
Manufacturing Proces	ss Inf	formation														
Terminal Plating / Grid Array Material			Terminal Base Alloy		J-STD-020 MSL Ra	ating	Peak Prod	Process Body Tempe		ature Ma	ure Max Time at Peak Tem		perature	erature Number of Reflow		
Matte Tin (Sn) Comments					1		260			30 seconds			econds	3		
SC414MLTRT is REACH	l-com	pliant product, per	EU Regula	ation EC1907	/2006 to include	recent	addition	of SVHC	candid	date list	t of subs	stances in	June 2	014.		

Save the fields in Import fields from a Clear all of the Lock the fields on this **Export Data** Import Data Reset Form Lock Supplier Fields this form to a file file into this form fields on this form form to prevent changes **RoHS Material Composition Declaration Declaration Type \*** Detailed Rohs Directive Rohs Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenvls (PBB). Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium 2002/95/EC Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2002/95/EC and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a ?RoHS restricted substance?) in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier?s liability and the Company?s remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply. 1 - Item(s) does not contain RoHS restricted substances per the definition above Supplier Acceptance \* Accepted **RoHS Declaration \*** Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions. **Declaration Signature** 

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

## **Homogeneous Material Composition Declaration for Electronic Products**

**Subltem Instructions:** The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

**Substance Instructions:** [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

1   1   1   1   1   1   1   1   1   1			Item/SubItem			Homogeneous	Weight	Unit of			Level	Substance Category			Substance	CAS	Evemnt	Weight	Unit of	Tolera	ance	PPM
## 1 Lead frame #M M C194 Ag plated C16.43 mg +C C Supplier #\$ -\$ Cu 7440-50-8 15.87 mg      ## 1 Lead frame #M M C194 Ag plated C16.43 mg +C C Supplier      ## 2 C A Lead/Lead Compound			Name			Material	weight	Measure			Level	Substance Category			Substance	CAS	Exempt	weight	Measure	-	+	FFIVI
+C -C A Lead/Lead Compound +S -S Lead 7439-89-6 0.37 mg	+I	-I	Die	+M	ı -M	Doped Silicon	2.25	mg	+C	-C	Supplier		+S	-S	Si	7440-21-3		2.25	mg			49,342
+C -C A Lead/Lead Compound +S -S Lead 7439-92-1 0 mg	+I	-1	Lead frame	+M	I -M	C194 Ag plated	16.43	mg	+C	-C	Supplier		+S	-S	Cu	7440-50-8		15.87	mg			348,02
+C -C supplier		,				_	•						+S	-s	Fe	7439-89-6		0.37	mg			8,128.5
+\$ -\$ Z									+C	-C	A	Lead/Lead Compound	+S	-s	Lead	7439-92-1		0	mg			10.809
+S -S Ag 7440-22-4 0.16 mg 1 1 1 Die attach material +M -M QMI519 Conduct 0.58 mg +C -C Supplier +S -S Ag 7440-22-4 0.41 mg 1 2 2 3 3 3 3 3 3 3 3 3 3 3 3 3 3 3 3 3									+C	-C	Supplier		+S	-s	Phosphorus	7723-14-0		О	mg			86.473
+1													+S	-s	z	7440-66-6		0.021	mg			457.58
+S -S Carbocycllic Acrylate Proprietary 0.12 mg 2.2 mg 4.5 -S Bismaleimide resin Proprietary 0.017 mg 2.2 mg 2.3 mg 4.5 -S Bismaleimide resin Proprietary 0.017 mg 2.3 mg 4.5 -S Acrylate Proprietary 0.0174 mg 2.3 mg 4.5 -S Additive Proprietary 0.0174 mg 2.3 mg 4.5 -S Additive Proprietary 0.0174 mg 2.3 mg 4.5 -S Additive Proprietary 0.0174 mg 2.3 mg 4.5 -S Others Proprietary 0.00009 mg 4.5 -S Others Proprietary 0.00009 mg 4.5 -S Others Proprietary 0.00009 mg 4.5 -S Silica fused 60676-86-0 22.91 mg 4.5 -S Epoxy resin Proprietary 0.734 mg 4.5 -S Epoxy resin Propri													+S	-s	Ag	7440-22-4		0.16	mg			3,603.0
+S -S Bismaleimide resin Proprietary 0.017 mg	+I	-1	Die attach material	+M	ı -M	QMI519 Conduct	0.58	mg	+C	-C	Supplier		+S	-s	Ag	7440-22-4		0.41	mg			9,030.7
+S -S Acrylate Proprietary 0.0174 mg 1 3 4 5 -S Additive Proprietary 0.0174 mg 1 3 5 -S Additive Proprietary 0.0174 mg 1 3 5 -S Additive Proprietary 0.0174 mg 1 3 5 -S Au 1 40-57-5 0.87 mg 1 4 5 -S Others Proprietary 0.00009 mg 1 5 -S Silica fused 60676-86-0 22.91 mg 1 5 -S Silica fused 60676-86-0 22.91 mg 1 5 -S Silica fused Proprietary 0.734 mg 1 5 -S Silica fu		·				_	•						+S	-s	Carbocycllic Acrylate	Proprietary		0.12	mg			2,543.8
+S -S Additive Proprietary 0.0174 mg 1.1 Wire bonding +M -M Gold 0.87 mg +C -C Supplier +S -S Au 7440-57-5 0.87 mg 1.1   +S -S others Proprietary 0.00009 mg 1.1   +I -I Encapsulation +M -M EME-G770HCD 24.45 mg +C -C Supplier +S -S Silica fused 60676-86-0 22.91 mg 1.5   +S -S Epoxy resin Proprietary 0.734 mg 1.5   +S -S Epoxy resin Pro													+S	-s	Bismaleimide resin	Proprietary		0.017	mg			381.57
+I       -I       Wire bonding       +M       -M       Gold       0.87       mg       +C       -C       Supplier       +S       -S       Au       7440-57-5       0.87       mg       1         +I       -I       Encapsulation       +M       -M       EME-G770HCD       24.45       mg       +C       -C       Supplier       +S       -S       Silica fused       60676-86-0       22.91       mg       -S         +S       -S       Epoxy resin       Proprietary       0.734       mg       -S													+S	-s	Acrylate	Proprietary		0.0174	mg			381.57
+S -S others Proprietary 0.00009 mg 1 -1   -1   Encapsulation													+S	-s	Additive	Proprietary		0.0174	mg			381.57
+I       -I       Encapsulation       +M       -M       EME-G770HCD       24.45       mg       +C       -C       Supplier       +S       -S       Silica fused       60676-86-0       22.91       mg       5         +S       -S       Epoxy resin       Proprietary       0.734       mg       -	+I	-1	Wire bonding	+M	ı -M	Gold	0.87	mg	+C	-C	Supplier		+S	-S	Au	7440-57-5		0.87	mg			19,077
+S -S Epoxy resin Proprietary 0.734 mg		•		,		_							+S	-s	others	Proprietary		0.00009	mg			1.9078
	+I	-1	Encapsulation	+M	ı -M	EME-G770HCD	24.45	mg	+C	-C	Supplier		+S	-s	Silica fused	60676-86-0		22.91	mg			502,40
S S Phonol rosin Proprietory 0 272						_	•	•					+S	-s	Epoxy resin	Proprietary		0.734	mg		'	16,085
+3 -3  Friedric resin   Frophetary   0.073   mg													+S	-s	Phenol resin	Proprietary		0.073	mg			1,608.5
+I -I Lead Finish +M -M Tin 1.02 mg +C -C Supplier +S -S Sn 7440-31-5 1.02 mg 2	+I	-1	Lead Finish	+M	I -M	Tin	1.02	mg	+C	-c	Supplier		+S	-S	Sn	7440-31-5		1.02	mg			22,366
+S -S Others Proprietary 0 mg				,	•			1					+S	-s	Others	Proprietary		0	mg			2.2368